

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZISHENG CAO	10/10/2016
JUNPING MA	10/11/2016
XING CHEN	10/11/2016
MINGYU WANG	10/10/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SZ DJI TECHNOLOGY CO., LTD.
<b>Street Address:</b>	6/F HKUST SZ IER BLDG., NO. 9 YUEXING 1ST ROAD
<b>Internal Address:</b>	HI-TECH PARK (SOUTH), NANSHAN DISTRICT
<b>City:</b>	SHENZHEN CITY
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	518057
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15349773
<b>CORRESPONDENCE DATA</b>	
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<b>Address Line 1:</b>	901 NEW YORK AVENUE, NW
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<b>ATTORNEY DOCKET NUMBER:</b>	13156.0048-00000
<b>NAME OF SUBMITTER:</b>	MONICA J. FREEMAN
<b>SIGNATURE:</b>	/monicajfreeman/
<b>DATE SIGNED:</b>	11/15/2016
<b>Total Attachments: 2</b>	
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## ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)), of an invention entitled:

**SYSTEM AND METHOD FOR SUPPORTING IMAGE DENOISING BASED ON NEIGHBORHOOD BLOCK  
DIMENSIONALITY REDUCTION**

as disclosed and claimed in Application No. \_\_\_\_\_, filed \_\_\_\_\_, United States Application No. \_\_\_\_\_,  
filed \_\_\_\_\_ (Confirmation No. \_\_\_\_\_) and/or PCT International Application No. PCT/CN2015/079093, filed  
May 15, 2015 and;

WHEREAS, **SZ DJI TECHNOLOGY CO., LTD.**, a corporation of China whose post office address is **6/F HKUST SZ IER Bldg., No. 9 Yuexing 1<sup>st</sup> Road, Hi-Tech Park (South), Nanshan District, Shenzhen City 518057, P.R. China** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to all applications for patents on this invention in all countries throughout the world, including any PCT International Application and all national stage applications based thereon that may be filed, and all patents issued upon such applications in all countries throughout the world;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, the above-referenced applications that disclose and claim this invention, any PCT International Application and all national stage applications based thereon that may be filed, any other applications for patents filed anywhere in the world that claim this invention, and all divisions, and continuations of any such application, and all patents which may be granted thereon, and all reissues thereof, and all rights to claim priority in any country on the basis of any such applications, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys empowered in the Power of Attorney in this application, to insert the filing date and application number of the above-referenced application(s) when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

1. LEGAL NAME OF SOLE OR FIRST INVENTOR <b>Zisheng CAO</b>	SIGNATURE <i>Zisheng Cao</i>	DATE <i>2016/10/10</i>
MAILING ADDRESS  6/F HKUST SZ IER Bldg., No. 9 Yuexing 1st Rd., Hi-Tech Park (South), Nanshan District, Shenzhen City 518057, P.R. China	RESIDENCE  <i>Shenzhen China.</i>	

2. LEGAL NAME OF SECOND INVENTOR, IF ANY <b>Junping MA</b>	SIGNATURE <i>Junping MA</i>	DATE <i>2016.10.11</i>
MAILING ADDRESS  6/F HKUST SZ IER Bldg., No. 9 Yuexing 1st Rd., Hi-Tech Park (South), Nanshan District, Shenzhen City 518057, P.R. China		RESIDENCE <i>shenzhen</i> <i>china</i>
3. LEGAL NAME OF THIRD INVENTOR, IF ANY <b>Xing CHEN</b>	SIGNATURE <i>Xing Chen</i>	DATE <i>2016-10-11</i>
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4. LEGAL NAME OF THIRD INVENTOR, IF ANY <b>Mingyu WANG</b>	SIGNATURE <i>Mingyu Wang</i>	DATE <i>2016.Oct.10</i>
MAILING ADDRESS  6/F HKUST SZ IER Bldg., No. 9 Yuexing 1st Rd., Hi-Tech Park (South), Nanshan District, Shenzhen City 518057, P.R. China		RESIDENCE <i>shenzhen</i> <i>China</i>